

**Microsemi Corporation**

August 26, 2016

**Product/Process Change Notification No: 2016-007****Subject:** Expansion of Assembly to the Philippines**Description of Change:**

It has come to our attention that a prior notice on this subject did not reach all customers and as a result, is now being re-issued with current status.

Microsemi DPG PDM gives notice of the expansion of manufacturing capacity to a wholly-owned manufacturing facility in Laguna, Philippines.

This site has the capability to assemble metal can, surface mount cavity, and glass sealed packages for commercial, JAN, JANTX, and JANTXV level products, as well as SCD's of these levels.

JANS level and export controlled product will not be assembled in the Philippines and are not included in this notification.

The Defense Logistics Agency (DLA) has audited the facility in 2014 and 2015 and approved this manufacturing site for MIL-PRF-19500 certification. Qualification lots were run to validate each process with the DLA per the full requirements of MIL-PRF-19500. The site is also AS9100C certified.

The screening and conformance testing for this product continues without change or interruption at the Ennis, Ireland facility for all other than the MOSFET product, which will continue to be tested in the Lawrence, MA facility.

The CDWR designation will remain to identify Lawrence, MA as the basic plant.

**Application Impact:**

Devices assembled at this manufacturing site are of the same design, form, fit, and function as those assembled in Lawrence, MA.

**Method of Identifying Changed Product:**

For JAN, JANTX, and JANTXV part numbers, the fab and assembly location is identified on the C of C and by a date code prefix as required by MIL-PRF-19500 and as listed in the QML / QPDSIS-19500:

Die Source	Assembly location	Date code prefix
Microsemi Lawrence, MA	Philippines	L
Microsemi Garden Grove, CA	Philippines	M
Microsemi Bend, OR	Philippines	D
Bourns, UK	Philippines	P

For SCD products with JAN, TX, TXV equivalence, fab and assembly locations are listed on the C of C. For commercial product, the C of C will remain unchanged.

**Products Affected by this Change:**

Commercial, JAN, JANTX, and JANTXV level products, as well as SCD's of these levels, built in the following packages are affected:

Metal cavity packages		Glass body packages
TO-3	TO-254	DO-35
TO-5	TO-257	DO-41
TO-18	DIP	DO-213AA
TO-24	Flatpack	DO-213AB
TO-33	U	A-body
TO-39	UA	B-body
TO-46	UB	C-body
TO-66	U3	D-body
TO-72	U4	A-body US
TO-78	DO-13	B-body US
TO-111		C-body US
TO-208		D-body US

**Production Shipment Schedule:**

This expansion does not affect delivery schedules.

**Contact Information:**

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Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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